



ZIF CONTACTS

SELECTION AND DESIGN OF THE INTERFACE AT RIGID.FLEX

Werner Öchslen

WÜRTH ELEKTRONIK MORE THAN YOU EXPECT

AGENDA

ZIF contacts - selection and design of the interface at RIGID.flex

1. ZIF-interface
 - Applications and advantages
2. ZIF-connector types
 - Types
3. ZIF-contacts
 - Similarities
 - Laser cutting
 - Differences
 - stackups
 - surfaces
4. ZIF-interface
 - Application conditions
 - Tips und tricks
 - summary



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Technisches Projektmanagement



ZIF-INTERFACE

Applications and advantages

ZIF = Zero Insertion Force

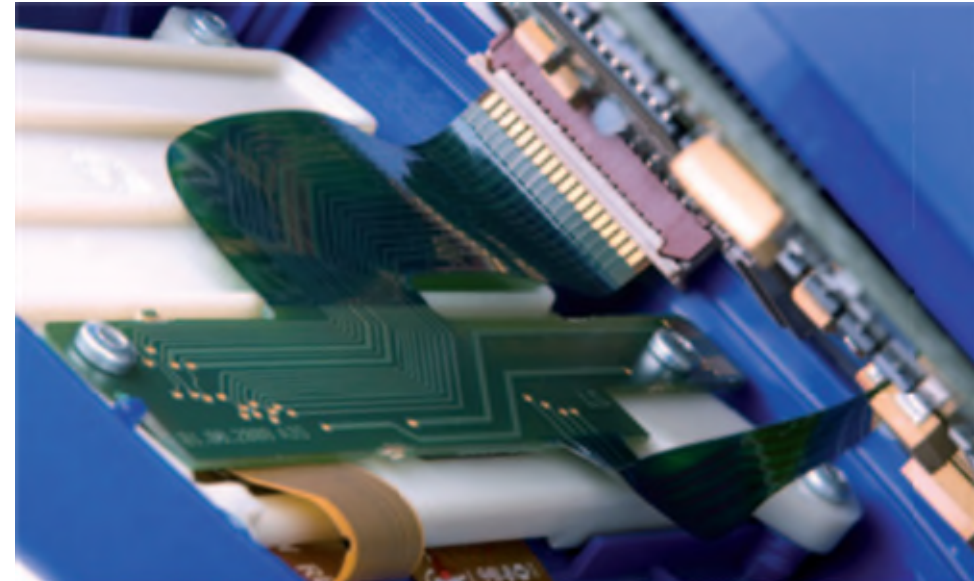
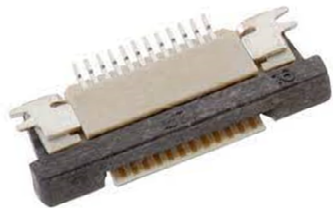
- Detachable and cost-effective connection solution
- Modular system structure
- Low construction heights
- Connection via ribbon cable (FFC)
- Customized Flex / Rigid-Flex Printed Circuit Board (FPC)

ZIF-INTERFACE =

ZIF-connector

+

FPC ZIF-contact



ZIF-CONNECTOR TYPES

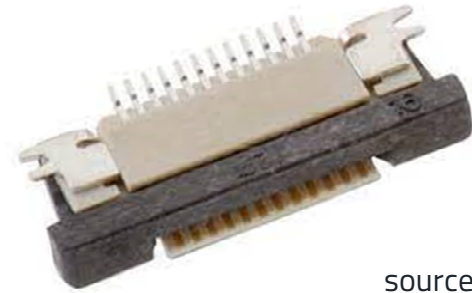
Examples

ZIF-types

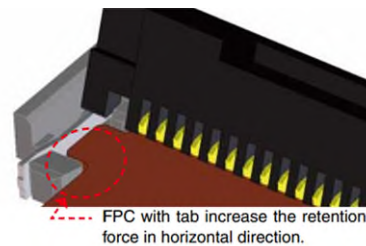
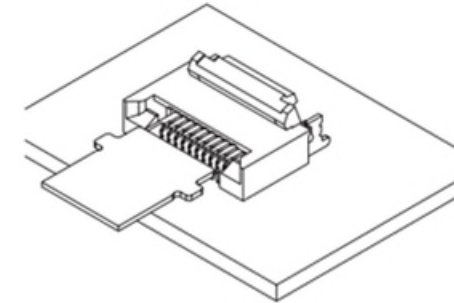
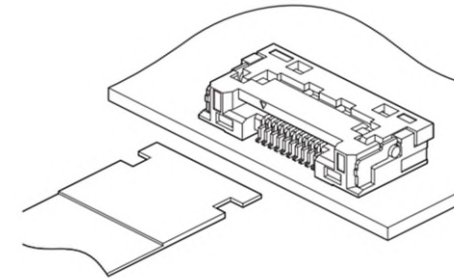
- BACKLOCK
- FRONTLOCK
- FLIPLOCK
- NON-ZIF (LIF)
- ...

Options

- number of contacts
- pitch of the contacts
- Surface
- Case height
- "HIGH SPEED"
- Locking
- Contacting above and/or below
- Area of application
- 1/2 – row contacts
- Standing / Lying
- ...

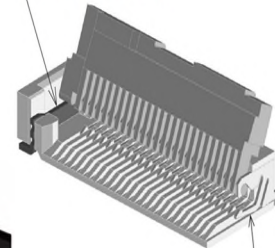


source: WE



Secure actuator lock and retention

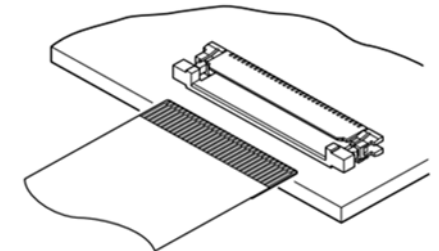
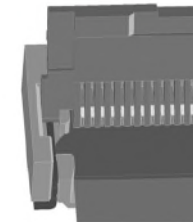
Hold in place by metal fittings



Hold in place by contacts

source:
Hirose

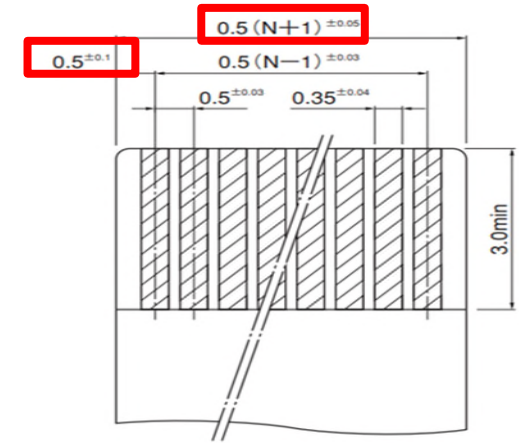
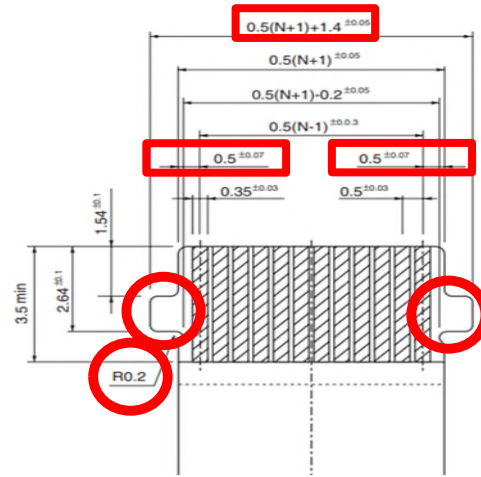
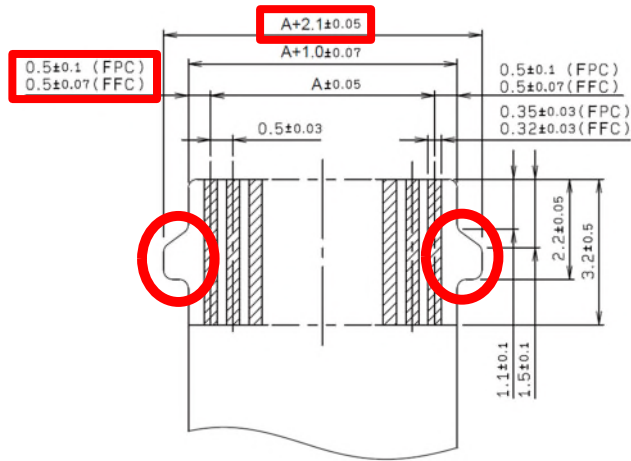
FPC temporary hold protrusion



source: JST

ZIF-CONTACTS

Similarities



Similarities

- Small contour tolerances
- Small tolerances contacts to the contour
- Small radii at the interlocks

Consequences for production

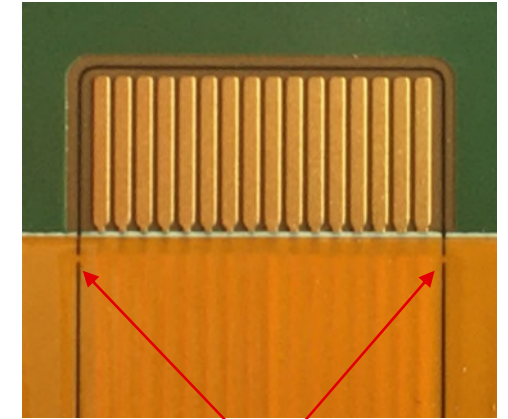
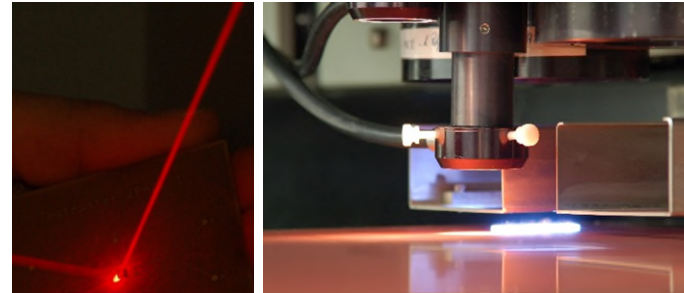
- Tolerances and radii not possible via milling process
- Contour processing generally by laser cutting

ZIF-CONTACTS

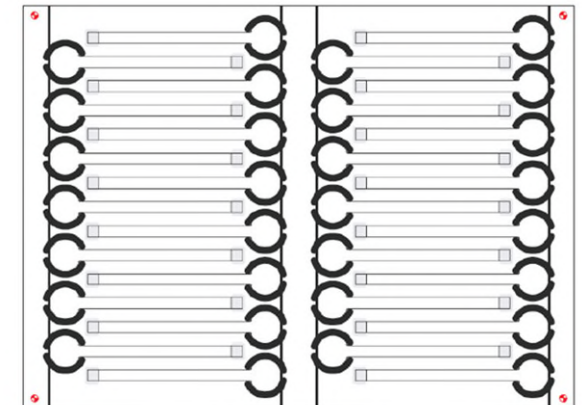
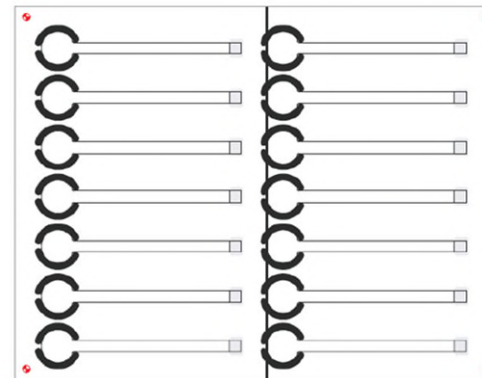
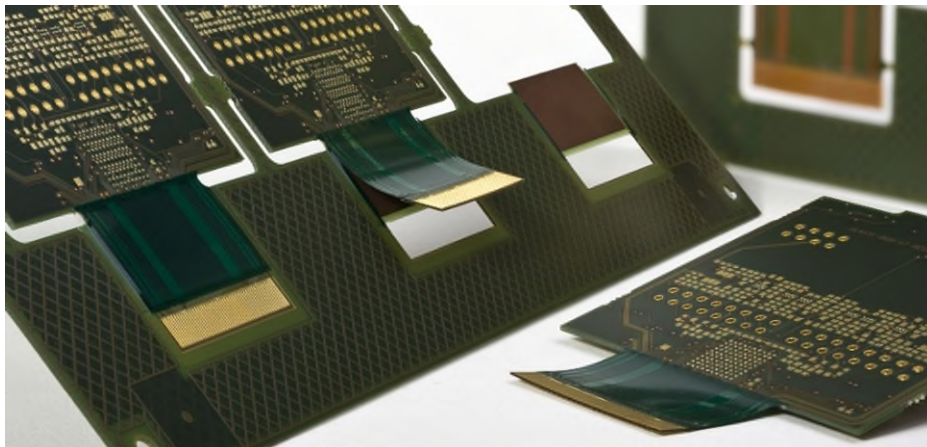
Laser cutting

Lasercutting of the ZIF-contact and flex area

- Registration of the laser via the conductive pattern
- Connection via laser micro bridges in the delivery panels
- "simpler" depaneling
- Delivery panel more stable (FR4 remains unglued under the flexarea)
- Optimized delivery panel design with smaller distances



Laser micro bridges



ZIF-CONTACTS

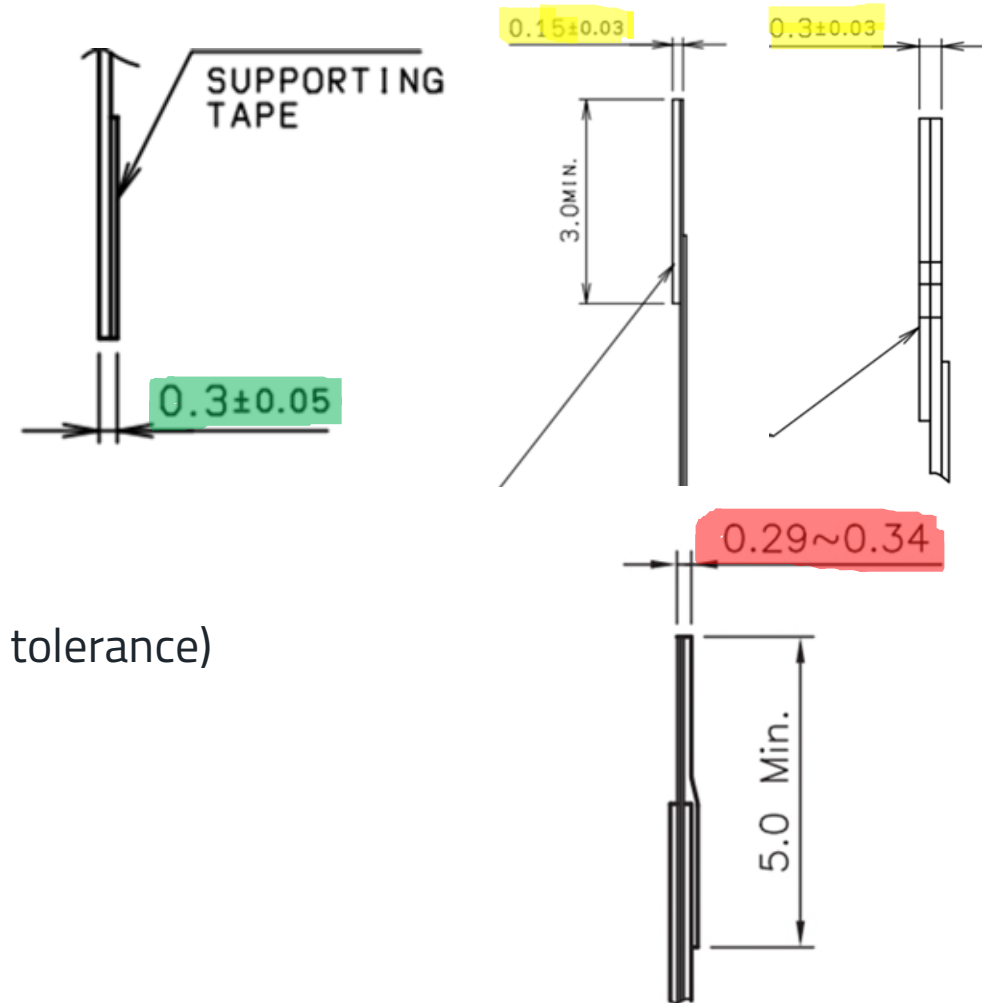
Differences

Thickness tolerance

- Standard tolerance +/- 0,05mm
- Advanced requirements +/- 0,03mm
- Smaller tolerances for PCB production not possible
 - FFC tolerance 0,29-0,34mm not produceable

Consequences for production

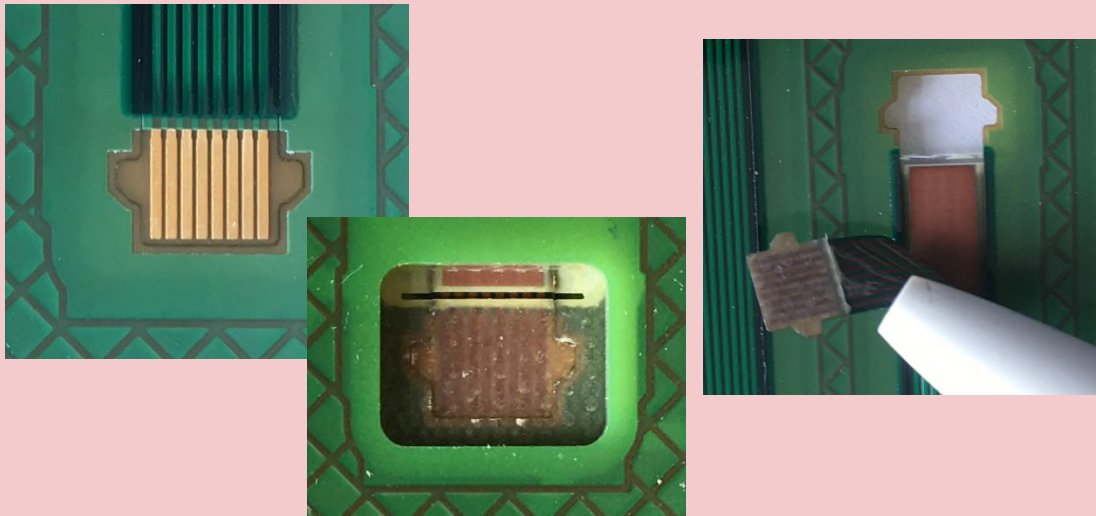
- Standard: FR4 stiffener via depthmilling (+/- 0,05mm tolerance)
- Advanced: Polyimid stiffener (+/- 0,03mm tolerance)



ZIF-CONTACTS

Stackups

Standard: FR4 - Stiffener



- Recommended standard
- Via automated depth milling process
- Thickness tolerance +/- 0.05mm

Advanced: Polyimid- Stiffener



- More effort + higher costs
- Polyimide stiffeners must be inserted manually
- Thickness tolerance +/- 0.03mm

ZIF-CONTACTS

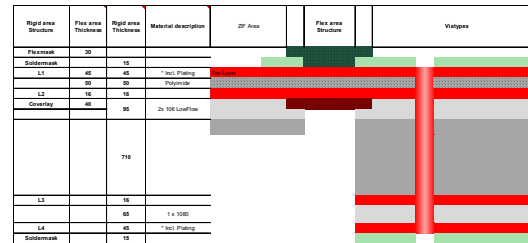
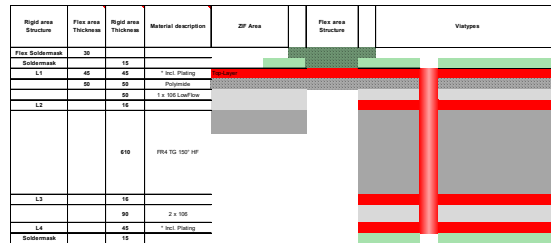
Stackups

1F-xRi stack

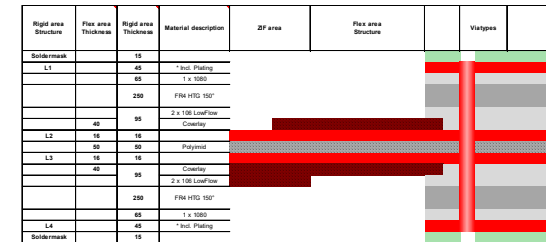
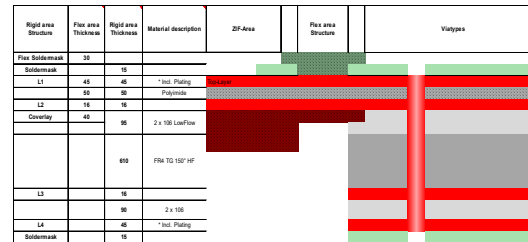
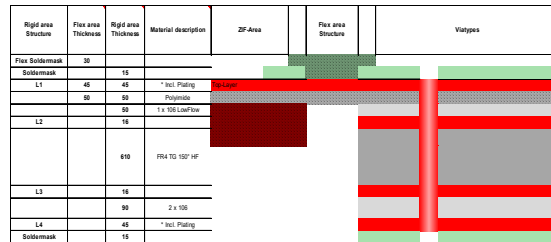
2F-xRi stack

xRi-2F-xRi stack

FR4 Stiffener



Polyimid Stiffener



ZIF-CONTACTS

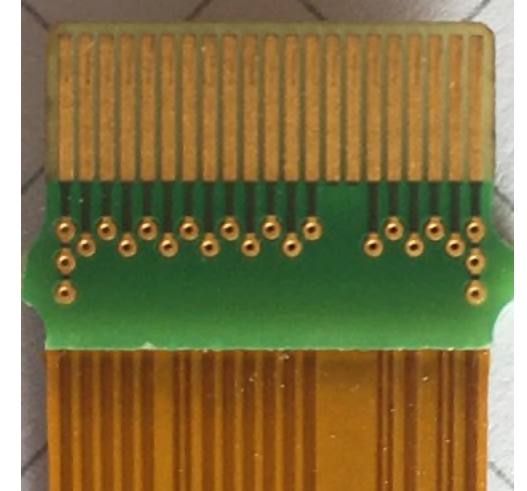
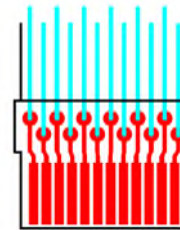
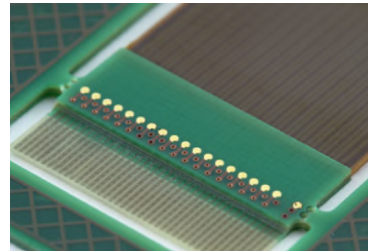
Cheaper alternative stackup

xRi-2F-xRi stack

Rigid area Structure	Flex area Thickness	Rigid area Thickness	Material description	ZIF area	Flex area Structure	Viatypes
Soldermask		15				
L1		45	* Solt. Plating			
		65	1 x 10/20			
		200	FR4 HTD 150°			
		55	2 x 106 LowFlow			
		40	Coverlay			
L2	16	16	Polyimid			
	50	50				
L3	16	16	Polyimid			
	40	40	Coverlay			
		55	2 x 106 LowFlow			
		200	FR4 HTD 150°			
		45	1 x 10/20			
L4		45	* Solt. Plating			
Soldermask		15				

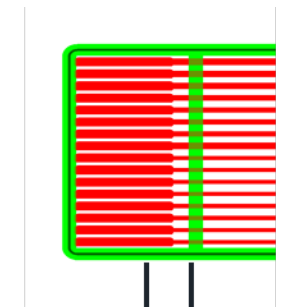
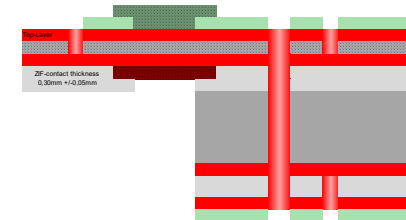
xRi-2F-xRi stack

- Switch via vias to the outer layer
- Rigid part in front of the ZIF-contact



2F-xRi stack

- Production „simpler“ compared to an xRi-2F-xRi stack
- Layerchange in the flexarea possible
- Contacting to the reference layer is possible via microvias

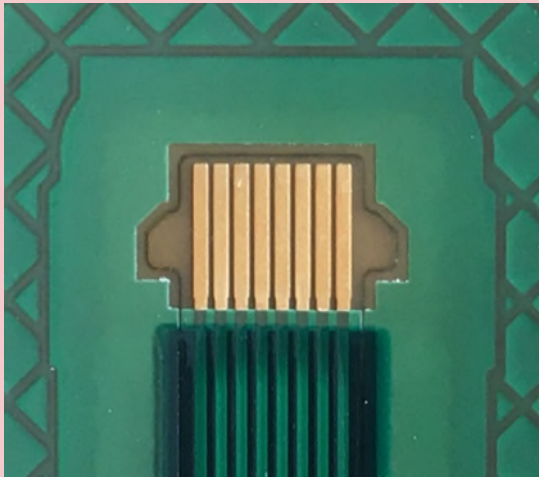


Bereich für Microvias
(nicht im Kontaktierbereich)

ZIF-CONTACTS

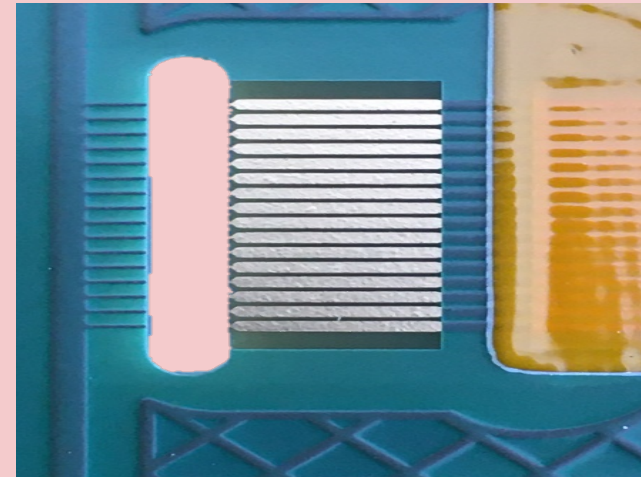
Surfaces

Immersion Ni/Au



- Au thickness $0,05\mu\text{m} - 0,10\mu\text{m}$
- Recommended standard surface

Galv. Gold / Hardgold



- Au thickness $1\mu\text{m} - 3\mu\text{m}$
- Gold connections necessary to panel border
- The front side must be milled because lasercutting is not possible (danger of copper burrs)
- More effort + higher costs

ZIF-INTERFACE

Application conditions

- Cheap, but not reliable connection
- No dynamic forces may act on the interface
 - No dynamic bending stress
 - No high vibration load
- The gold layer can be rubbed off through the spring contacts (mostly with NON-ZIF; LIF)
- contacts at the transition from the ZIF housing can break
- Other plug connections are recommended for a reliable connection under vibration, dynamic bending, ...



ZIF-INTERFACE

Tips und Tricks

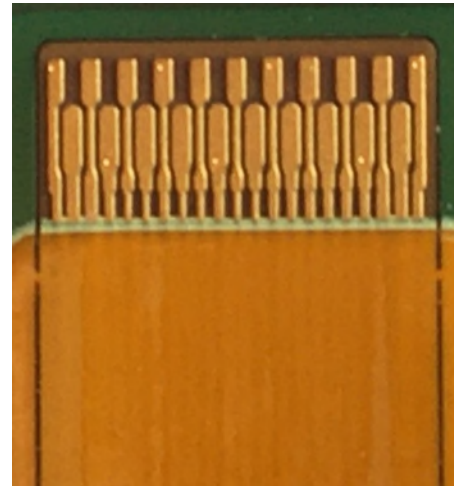
Better Handling

- „Ears“ at the stiffener area



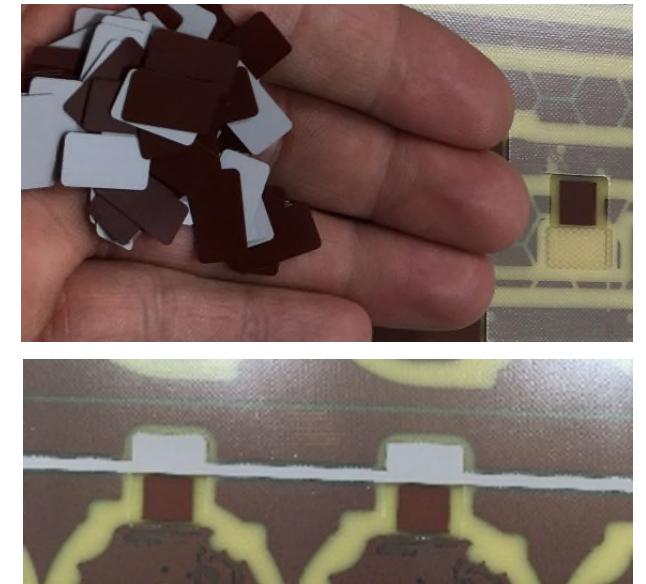
2-row Version

- Pitch 0,30mm
- Min. isolation diastances >100µm (possibly the layout can be modified)



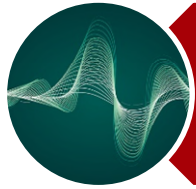
Polyimid-Stiffener

- ZIF contacts in a row for easier handling
- Stiffener is inserted by a stripe (no single part)

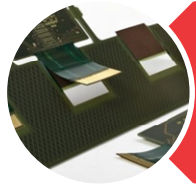


ZIF-INTERFACE

Summary



ZIF interfaces are not suitable for all application conditions



Laser cutting enables small contour tolerances and an optimized delivery panel design.



The selection of a suitable ZIF connector and the PCB stackup saves effort and costs.



We can support you with the correct selection of connectors, the circuit board structure and the design of the delivery panel

THANK YOU FOR YOUR ATTENTION

ZIF contacts

selection and design of the interface at RIGID.flex